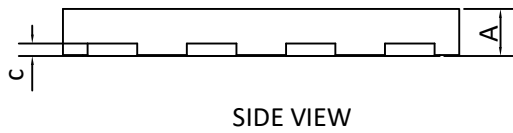
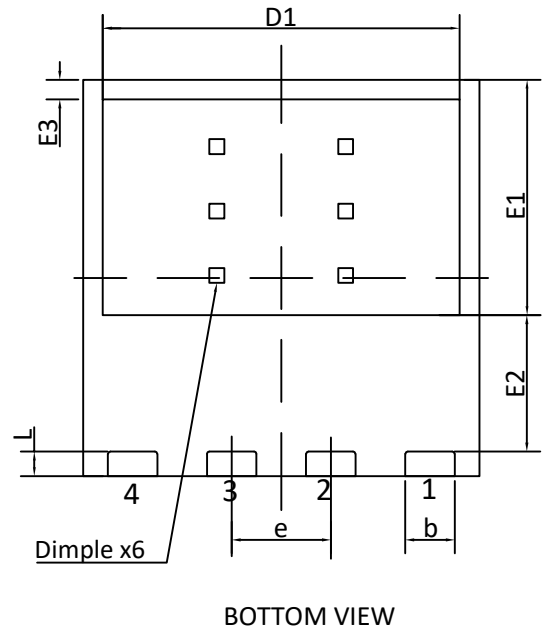
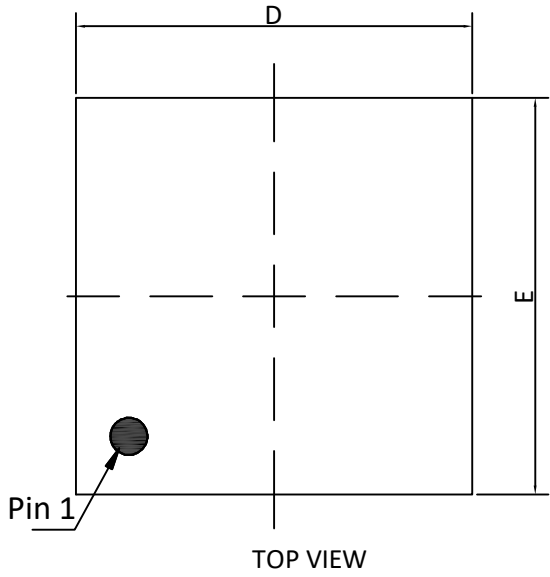
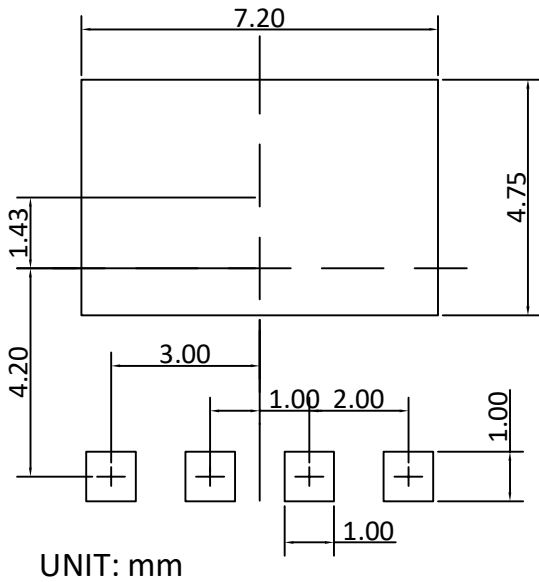


DFN8x8_4L_EP1_S PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



SYMBOLS	DIM. IN MM			DIM. IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.800	---	1.100	0.031	---	0.043
A1	0.000	---	0.050	0.000	---	0.002
D	7.900	8.000	8.100	0.311	0.315	0.319
D1	7.100	7.200	7.300	0.279	0.283	0.287
E	7.900	8.000	8.100	0.311	0.315	0.319
E1	4.650	4.750	4.850	0.183	0.187	0.191
E2	2.650	2.750	2.850	0.104	0.108	0.112
E3	0.300	0.400	0.500	0.012	0.016	0.020
b	0.900	1.000	1.100	0.035	0.039	0.043
e	2.00(BSC)			0.079(BSC)		
c	0.150	0.250	0.350	0.006	0.010	0.014
L	0.400	0.500	0.600	0.016	0.020	0.024

NOTE

1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
2. CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
3. THIS PACKAGE WAS QUALIFIED USING IR REFLOW PROCESS (JEDEC STANDARD). FOR USAGE IN OTHER SOLDERING PROCESSES, PLEASE CONTACT LOCAL AOS REPRESENTATIVES.